Product specification

BT137B series

GENERAL DESCRIPTION

Passivated triacs in a plastic envelope suitable for surface mounting, intended for use in applications requiring high bidirectional transient and blocking voltage capability and high thermal cycling performance. Typical applications include motor control, industrial and domestic lighting, heating and static switching.

QUICK REFERENCE DATA

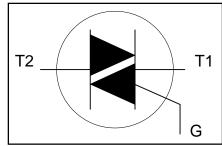
SYMBOL	PARAMETER	MAX.	MAX.	UNIT
	BT137B- BT137B- BT137B- BT137B-	600 600F 600G	800 800F 800G	
V _{DRM}	Repetitive peak off-state	600	800	V
I _{T(RMS)} I _{TSM}	voltages RMS on-state current Non-repetitive peak on-state current	8 65	8 65	A A

PINNING - SOT404

PIN DESCRIPTION -1 main terminal 1 T2 2 main terminal 2 -D-3 gate 2 main terminal 2 mb 1 3

PIN CONFIGURATION

SYMBOL



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MA	AX.	UNIT
V _{drm}	Repetitive peak off-state voltages		-	-600 600 ¹	-800 800	V
I _{T(RMS)} I _{TSM}	RMS on-state current Non-repetitive peak on-state current	full sine wave; $T_{mb} \le 102$ °C full sine wave; $T_j = 25$ °C prior to surge	-	8	3	A
		t = 20 ms t = 16.7 ms	-	6 7	5	A
l²t dI⊤/dt	l ² t for fusing Repetitive rate of rise of on-state current after	t = 10 ms I_{TM} = 12 A; I_G = 0.2 A; dI_G/dt = 0.2 A/µs	-	2		A A ² s
	triggering	T2+ G+ T2+ G- T2- G- T2- G+		5 5	0 0 0 0	A/μs A/μs A/μs A/μs
I _{GM} V _{GM} P _{GM}	Peak gate current Peak gate voltage Peak gate power		- - -		2 5 5	A V W
$\begin{array}{c} P_{G(AV)} \\ T_{stg} \\ T_{j} \end{array}$	Average gate power Storage temperature Operating junction temperature	over any 20 ms period	- -40 -	15	.5 50 25	°℃ ℃

¹ Although not recommended, off-state voltages up to 800V may be applied without damage, but the triac may switch to the on-state. The rate of rise of current should not exceed 6 $A/\mu s$.

BT137B series

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R _{th j-mb} R _{th j-a}	Thermal resistance junction to mounting base Thermal resistance junction to ambient	full cycle half cycle minimum footprint, FR4 board	- -	- - 55	2.0 2.4 -	K/W K/W K/W

STATIC CHARACTERISTICS

 $T_j = 25$ °C unless otherwise stated

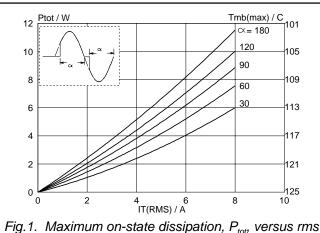
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.		MAX.		UNIT
I _{GT}	Gate trigger current	BT137B- V _D = 12 V; I _T = 0.1 A				F	G	
·GI		T2+ G+ T2+ G-	-	5 8	35 35	25 25	50 50	mA mA
		T2- G- T2- G+	-	11 30	35 70	25 70	50 100	mA mA
I _L	Latching current	$V_{D} = 12 \text{ V}; \text{ I}_{GT} = 0.1 \text{ A}$ T2+ G+ T2+ G-	-	7 16	30 45	30 45	45 60	mA mA
I _H	Holding current	T2- G- T2- G+ V _D = 12 V; I _{GT} = 0.1 A		5 7 5	30 45 20	30 45 20	45 60 40	mA mA mA
V _T V _{GT}	On-state voltage Gate trigger voltage	$I_{T} = 10 \text{ A}$ $V_{D} = 12 \text{ V}; I_{T} = 0.1 \text{ A}$ $V_{D} = 400 \text{ V}; I_{T} = 0.1 \text{ A};$	- - 0.25	1.3 0.7 0.4		1.65 1.5 -	I	
I _D	Off-state leakage current	$T_{j}^{-} = 125 \ ^{\circ}C$ $V_{D} = V_{DRM(max)};$ $T_{j} = 125 \ ^{\circ}C$	-	0.1		0.5		mA

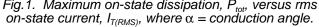
DYNAMIC CHARACTERISTICS

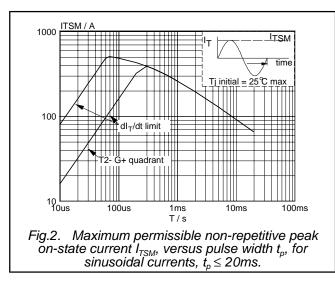
 $T_i = 25$ °C unless otherwise stated

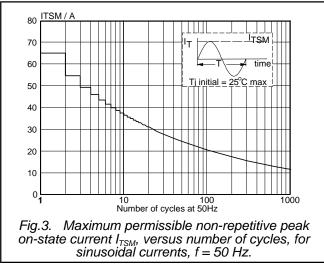
SYMBOL	PARAMETER	CONDITIONS		MIN.		TYP.	MAX.	UNIT
dV _D /dt	Critical rate of rise of off-state voltage	BT137B- $V_{DM} = 67\% V_{DRM(max)};$ $T_i = 125 °C; exponential$	 100	F 50	G 200	250	-	V/µs
dV _{com} /dt	Critical rate of change of commutating voltage	waveform; gate open circuit $V_{DM} = 400 \text{ V}; \text{ T}_{j} = 95 ^{\circ}\text{C};$ $I_{T(RMS)} = 8 \text{ A};$ $dI_{com}/dt = 3.6 \text{ A/ms}; gate$	-	-	10	20	-	V/µs
t _{gt}	Gate controlled turn-on time	open circuit $I_{TM} = 12 \text{ A}; V_D = V_{DRM(max)};$ $I_G = 0.1 \text{ A}; dI_G/dt = 5 \text{ A}/\mu \text{s}$	-	-	-	2	-	μs

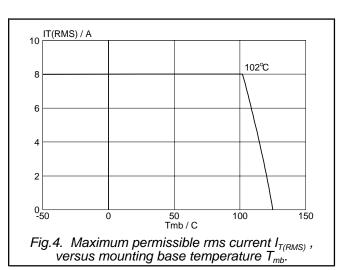
BT137B series











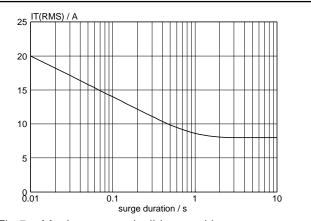
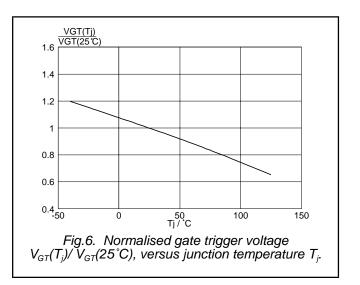
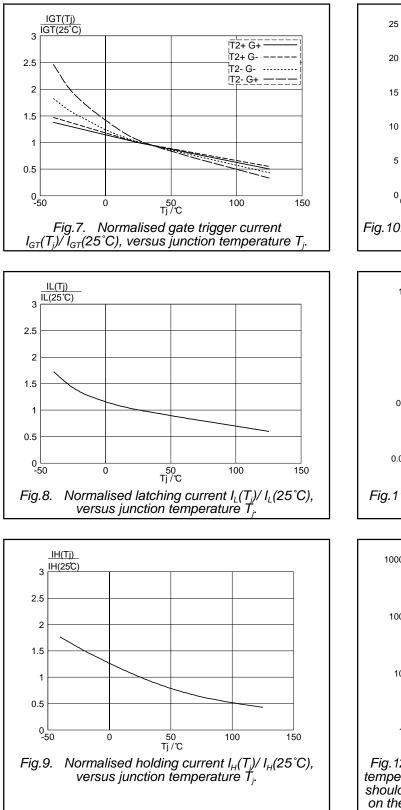
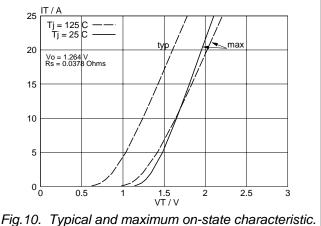


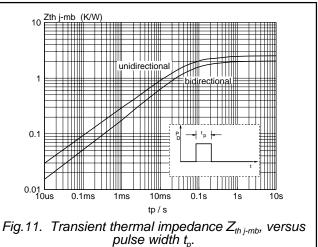
Fig.5. Maximum permissible repetitive rms on-state current $I_{T(RMS)}$, versus surge duration, for sinusoidal currents, f = 50 Hz; $T_{mb} \le 102$ °C.

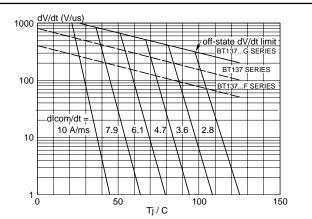


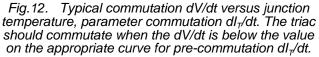
BT137B series





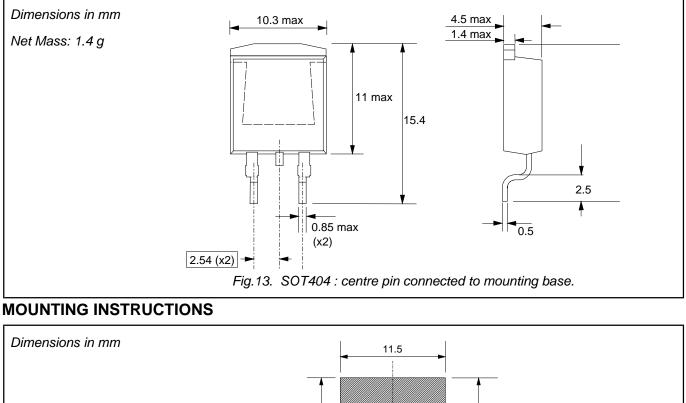






BT137B series

MECHANICAL DATA



9.0 9.0 fig. 14. SOT404 : minimum pad sizes for surface mounting.

Notes

1. Plastic meets UL94 V0 at 1/8".

Product specification

BT137B series

DEFINITIONS

DATA SHEET STATUS					
DATA SHEET STATUS ²	PRODUCT STATUS ³	DEFINITIONS			
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice			
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in ordere to improve the design and supply the best possible product			
Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Changes will be communicated according to the Customer Product/Process Change Notification (CPCN) procedure SNW-SQ-650A			
Limiting values					

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

© Philips Electronics N.V. 2001

All rights are reserved. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner.

The information presented in this document does not form part of any quotation or contract, it is believed to be accurate and reliable and may be changed without notice. No liability will be accepted by the publisher for any consequence of its use. Publication thereof does not convey nor imply any license under patent or other industrial or intellectual property rights.

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices or systems where malfunction of these products can be reasonably expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

² Please consult the most recently issued datasheet before initiating or completing a design.

³ The product status of the device(s) described in this datasheet may have changed since this datasheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.